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# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











## **N-Channel Power MOSFET**

800V, 5.5A, 1.2Ω

#### **FEATURES**

- Super-Junction technology
- High performance due to small figure-of-merit
- High ruggedness performance
- High commutation performance
- Pb-free plating
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

| KEY PERFORMANCE PARAMETERS |      |    |  |
|----------------------------|------|----|--|
| PARAMETER VALUE UNIT       |      |    |  |
| $V_{DS}$                   | 800  | V  |  |
| R <sub>DS(on)</sub> (max)  | 1.2  | Ω  |  |
| $Q_{g}$                    | 19.4 | nC |  |







#### **APPLICATIONS**

- Power Supply
- Lighting



| ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted) |                        |                                   |              |      |
|---|------------------------|-----------------------------------|--------------|------|
| PARAMETER   |                        | SYMBOL                            | LIMIT        | UNIT |
| Drain-Source Voltage  |                        | V <sub>DS</sub>                   | 800          | V    |
| Gate-Source Voltage   |                        | V <sub>GS</sub>                   | ±30          | V    |
| Continuous Drain Current (Note 1)                                       | $T_C = 25^{\circ}C$    |                                   | 5.5          | Α    |
|   | T <sub>C</sub> = 100°C | I <sub>D</sub>                    | 3.4          | Α    |
| Pulsed Drain Current (Note 2)   |                        | I <sub>DM</sub>                   | 16.5         | Α    |
| Total Power Dissipation @ $T_C = 25^{\circ}C$                           | ;                      | P <sub>DTOT</sub>                 | 25           | W    |
| Single Pulse Avalanche Energy (Note 3                                   | 3)                     | E <sub>AS</sub>                   | 121          | mJ   |
| Single Pulse Avalanche Current (Note                                    | 3)                     | I <sub>AS</sub>                   | 2.2          | Α    |
| Operating Junction and Storage Tem                                      | perature Range         | T <sub>J</sub> , T <sub>STG</sub> | - 55 to +150 | °C   |

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| THERMAL PERFORMANCE                    |                  |       |      |  |
|--|------------------|-------|------|--|
| PARAMETER                              | SYMBOL           | LIMIT | UNIT |  |
| Junction to Case Thermal Resistance    | R <sub>eJC</sub> | 5     | °C/W |  |
| Junction to Ambient Thermal Resistance | $R_{\Theta JA}$  | 62    | °C/W |  |

**Notes:**  $R_{\Theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins.  $R_{\Theta JA}$  is guaranteed by design while  $R_{\Theta CA}$  is determined by the user's board design.  $R_{\Theta JA}$  shown below for single device operation on FR-4 PCB with minimum recommended footprint in still air.

| PARAMETER                                 | CONDITIONS   | SYMBOL              | MIN | TYP  | MAX  | UNIT |
|---|--|---------------------|-----|------|------|------|
| Static                                    |  |                     |     |      |      |      |
| Drain-Source Breakdown Voltage            | $V_{GS} = 0V, I_D = 250\mu A$  | BV <sub>DSS</sub>   | 800 |      |      | ٧    |
| Gate Threshold Voltage                    | $V_{DS} = V_{GS}, I_D = 250 \mu A$                                   | $V_{GS(TH)}$        | 2   |      | 4    | ٧    |
| Gate Body Leakage                         | $V_{GS} = \pm 30V$ , $V_{DS} = 0V$                                   | I <sub>GSS</sub>    |     |      | ±100 | nA   |
| Zero Gate Voltage Drain Current           | $V_{DS} = 800V, V_{GS} = 0V$   | I <sub>DSS</sub>    |     |      | 1    | μΑ   |
| Drain-Source On-State Resistance (Note 4) | V <sub>GS</sub> = 10V, I <sub>D</sub> = 1.8A                         | R <sub>DS(on)</sub> |     | 0.9  | 1.2  | Ω    |
| Dynamic (Note 5)                          |  |                     |     | l    | l    |      |
| Total Gate Charge                         | $V_{DS} = 380V, I_D = 5.5A,$   | $Q_g$               |     | 19.4 |      |      |
| Gate-Source Charge                        |  | $Q_{gs}$            |     | 3.4  |      | nC   |
| Gate-Drain Charge                         | $V_{GS} = 10V$   | $Q_{gd}$            |     | 9.6  |      |      |
| Input Capacitance                         | $V_{DS} = 100V, V_{GS} = 0V,$  | C <sub>iss</sub>    |     | 685  |      | . =  |
| Output Capacitance                        | f = 1.0MHz   | C <sub>oss</sub>    |     | 62   |      | pF   |
| Gate Resistance                           | F = 1MHz, open drain   | $R_g$               |     | 3.4  |      | Ω    |
| Switching (Note 6)                        |  |                     |     |      |      |      |
| Turn-On Delay Time                        |  | t <sub>d(on)</sub>  |     | 22   |      |      |
| Turn-On Rise Time                         | $V_{DD} = 380V,$ $R_{GEN} = 25\Omega,$ $I_{D} = 5.5A, V_{GS} = 10V,$ | t <sub>r</sub>      |     | 11   |      |      |
| Turn-Off Delay Time                       |  | t <sub>d(off)</sub> |     | 55   |      | ns   |
| Turn-Off Fall Time                        | $I_D = 3.3A$ , $V_{GS} = 10V$ ,                                      | t <sub>f</sub>      |     | 10   |      |      |
| Source-Drain Diode                        |  |                     |     |      |      |      |
| Forward On Voltage (Note 4)               | I <sub>S</sub> = 5.5A, V <sub>GS</sub> = 0V                          | $V_{SD}$            |     |      | 1.4  | V    |
| Reverse Recovery Time                     | $V_B = 100V, I_S = 5.5A$   | t <sub>rr</sub>     |     | 240  |      | ns   |
| Reverse Recovery Charge                   | $dI_F/dt = 100A/\mu s$   | Q <sub>rr</sub>     |     | 2.5  |      | μC   |

#### Notes:

- 1. Current limited by package.
- 2. Pulse width limited by the maximum junction temperature.
- 3. L = 50mH,  $I_{AS} = 2.2A$ ,  $V_{DD} = 50V$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^{\circ}C$
- 4. Pulse test: PW  $\leq$  300 $\mu$ s, duty cycle  $\leq$  2%.
- 5. For DESIGN AID ONLY, not subject to production testing.
- 6. Switching time is essentially independent of operating temperature.



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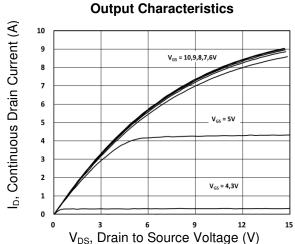
## **ORDERING INFORMATION**

| PART NO.        | PACKAGE | PACKING      |
|-----------------|---------|--------------|
| TSM80N1R2CI C0G | ITO-220 | 50pcs / Tube |

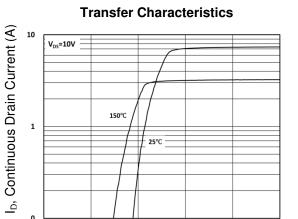


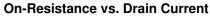
#### **CHARACTERISTICS CURVES**

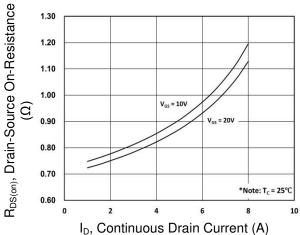
 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$ 





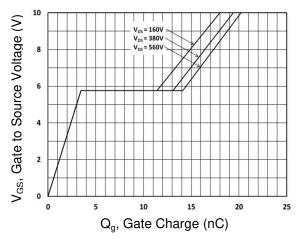




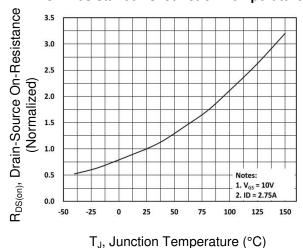


Gate-Source Voltage vs. Gate Charge

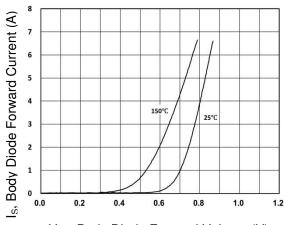
V<sub>GS</sub>, Gate to Source Voltage (V)



#### On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Current vs. Voltage



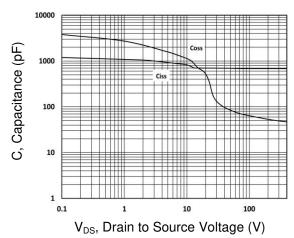
V<sub>SD</sub>, Body Diode Forward Voltage (V)



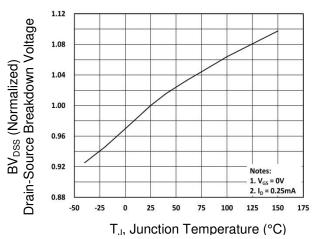
#### **CHARACTERISTICS CURVES**

 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$ 

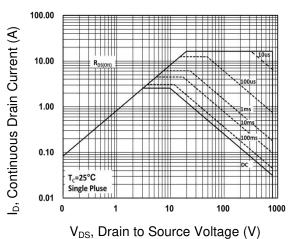
## Capacitance vs. Drain-Source Voltage



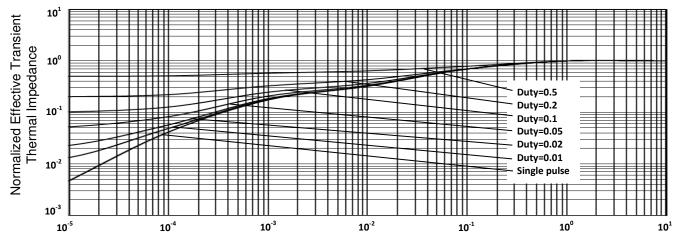
### BV<sub>DSS</sub> vs. Junction Temperature



#### **Maximum Safe Operating Area**



#### Normalized Thermal Transient Impedance, Junction-to-Case

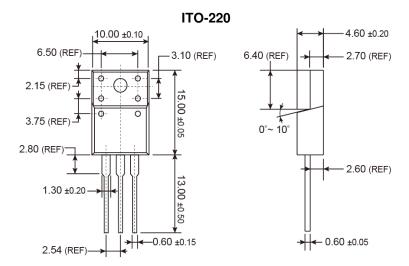


Square Wave Pulse Duration (s)



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### PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)



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## **MARKING DIAGRAM**



**G** = Halogen Free

Y = Year Code

**WW** = Week Code  $(01\sim52)$ 

F = Factory Code



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